

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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Email & Skype: info@chipsmall.com Web: www.chipsmall.com

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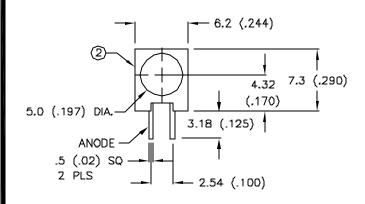


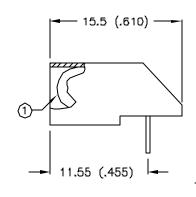
DATE REVISIONS REV

SSF-LXH1071YD

REV

UNCONTROLLED DOCUMENT





ELECTRO-OPTICAL	CHARA	CTERIS	TICS TA	.=25 °C	I _f =20mA
PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		585 (`	YELLQW)	nm	
FORWARD VOLTAGE		2.1	2.8	٧ _f	
REVERSE VOLTAGE	5.0			\vee_{r}	I _F =100u A
AXIAL INTENSITY		20		mcd	I _f = 20mA
VIEWING ANGLE		80		2x thet	g .
EMITTED COLOR:	YELL	OW			
EPOXY LENS FINISH:	YELL	OW DIFF	USED		

LIMITS OF SAFE OPE	RATION AT 25 DEI	G, C
PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	155	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	110	mW
DERATE FROM 25 °C	-1.2	mW/ □ C
OPERATING, STORAGE TEMP.	-55 TO +100	° C
LEAD SOLDERING TEMP.	+260	• C
1.6mm FROM BODY		5 SEC. MAX
<u> </u>		

^{*} t<10uS

NOTES:

- 1. SSL-LX509F3YD LED.
- 2. \$\$H-LXH1071 WHITE HOLDER.
- 3. TOLERANCE: +/-0.25 (+/-.010).

RELIABILITY NOTE:

OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE
THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND
FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING
PROCESS.

UNCONTROLLED DOCUMENT
FXH107AE



292 E. HELLEN ROAD PALATINE, ILLINOIS 60067 (708) 359-2790

DATE: 9-1-93

SCALE: N/A

APPROVED BY:

DRAWN BY:

T-5 (T-1 3/4) RIGHT ANGLE FAULT INDICATOR, YELLOW DIFFUSED

PAGE 1 OF 1

DRAWING NUMBER
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